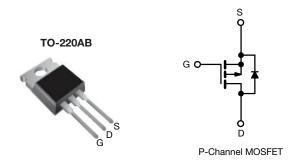


Vishay Siliconix

## **Power MOSFET**

PRODUCT SUMMARY					
V <sub>DS</sub> (V)	-60				
$R_{DS(on)}(\Omega)$	$V_{GS} = -10 \text{ V}$	0.14			
Q <sub>g</sub> max. (nC)	34				
Q <sub>gs</sub> (nC)	9.9				
Q <sub>gd</sub> (nC)	16				
Configuration	Single				



### **FEATURES**

- Dynamic dV/dt rating
- · Repetitive avalanche rated
- P-channel
- 175 °C operating temperature
- Fast switching
- Ease of paralleling
- Simple drive requirements
- Material categorization: for definitions of compliance please see <a href="https://www.vishav.com/doc?99912"><u>www.vishav.com/doc?99912</u></a>

#### Note

\* This datasheet provides information about parts that are RoHS-compliant and / or parts that are non-RoHS-compliant. For example, parts with lead (Pb) terminations are not RoHS-compliant. Please see the information / tables in this datasheet for details.

## **DESCRIPTION**

Third generation power MOSFETs from Vishay provide the designer with the best combination of fast switching, ruggedized device design, low on-resistance and cost-effectiveness.

The TO-220AB package is universally preferred for all commercial-industrial applications at power dissipation levels to approximately 50 W. The low thermal resistance and low package cost of the TO-220AB contribute to its wide acceptance throughout the industry.

ORDERING INFORMATION				
Package	TO-220AB			
Load (Dh) fron	IRF9Z34PbF			
Lead (Pb)-free	SiHF9Z34-E3			
SnPb	IRF9Z34			
SIIFU	SiHF9Z34			

PARAMETER	SYMBOL	LIMIT	UNIT	
Drain-Source Voltage	$V_{DS}$	-60		
Gate-Source Voltage	$V_{GS}$	± 20	V	
Continuous Drain Current	$V_{GS}$ at -10 V $\frac{T_C = 25 ^{\circ}\text{C}}{T_C = 100 ^{\circ}\text{C}}$	I <sub>D</sub>	-18	
Continuous Drain Current	$T_C = 100 ^{\circ}$ C		-13	Α
Pulsed Drain Current <sup>a</sup>		I <sub>DM</sub>	-72	
Linear Derating Factor		0.59	W/°C	
Single Pulse Avalanche Energy <sup>b</sup>	E <sub>AS</sub>	370	mJ	
Repetitive Avalanche Current a	I <sub>AR</sub>	-18	А	
Repetitive Avalanche Energy <sup>a</sup>	E <sub>AR</sub>	8.8	mJ	
Maximum Power Dissipation	$P_{D}$	88	W	
Peak Diode Recovery dV/dt <sup>c</sup>	dV/dt	-4.5	V/ns	
Operating Junction and Storage Temperature Range	T <sub>J</sub> , T <sub>stg</sub>	-55 to +175		
Soldering Recommendations (Peak temperature) <sup>d</sup>		300	°C	
Mounting Toyour	6 00 or M0 corour		10	lbf ⋅ in
Mounting Torque	6-32 or M3 screw		1.1	N⋅m

### **Notes**

- a. Repetitive rating; pulse width limited by maximum junction temperature (see fig. 11).
- b.  $V_{DD}$  = -25 V, starting  $T_J$  = 25 °C, L = 1.3 mH,  $R_g$  = 25  $\Omega$ ,  $I_{AS}$  = -18 A (see fig. 12).
- c.  $I_{SD} \le -18$  A,  $dI/dt \le 170$  A/µs,  $V_{DD} \le V_{DS}$ ,  $T_J \le 175$  °C.
- d. 1.6 mm from case.



# Vishay Siliconix

THERMAL RESISTANCE RATINGS					
PARAMETER	SYMBOL	TYP.	MAX.	UNIT	
Maximum Junction-to-Ambient	$R_{thJA}$	-	62		
Case-to-Sink, Flat, Greased Surface	R <sub>thCS</sub>	0.50	-	°C/W	
Maximum Junction-to-Case (Drain)	R <sub>thJC</sub>	-	1.7		

<b>SPECIFICATIONS</b> (T <sub>J</sub> = 25 °C, unless otherwise noted)							
PARAMETER	SYMBOL	TEST CONDITIONS		MIN.	TYP.	MAX.	UNIT
Static	<del>!</del>	+		ļ		l .	Į.
Drain-Source Breakdown Voltage	V <sub>DS</sub>	$V_{GS} = 0 \text{ V, } I_D = -250  \mu\text{A}$		-60	-	-	V
V <sub>DS</sub> Temperature Coefficient	ΔV <sub>DS</sub> /T <sub>J</sub>	Reference to	o 25 °C, I <sub>D</sub> = -1 mA	-	-0.060	-	V/°C
Gate-Source Threshold Voltage	V <sub>GS(th)</sub>	$V_{DS} = V_{C}$	<sub>GS</sub> , I <sub>D</sub> = 250 μA	-2.0	-	-4.0	V
Gate-Source Leakage	I <sub>GSS</sub>	V <sub>G</sub>	V <sub>GS</sub> = ± 20 V		-	± 100	nA
		V <sub>DS</sub> = -60 V, V <sub>GS</sub> = 0 V		-	-	-100	
Zero Gate Voltage Drain Current	I <sub>DSS</sub>		T <sub>GS</sub> = 0 V, T <sub>J</sub> = 150 °C	-	-	-500	μA
Drain-Source On-State Resistance	R <sub>DS(on)</sub>	V <sub>GS</sub> = -10 V	I <sub>D</sub> = -11 A <sup>b</sup>	-	_	0.14	Ω
Forward Transconductance	9 <sub>fs</sub>	V <sub>DS</sub> = -2	5 V, I <sub>D</sub> = -11 A <sup>b</sup>	5.9	-	_	S
Dynamic	U.S						
Input Capacitance	C <sub>iss</sub>		- 0 V	-	1100	_	
Output Capacitance	C <sub>oss</sub>		<sub>GS</sub> = 0 V, <sub>S</sub> = -25 V,	_	620	-	pF
Reverse Transfer Capacitance	C <sub>rss</sub>		MHz, see fig. 5	-	100	-	
Total Gate Charge	Qg			-	-	34	nC
Gate-Source Charge	Q <sub>gs</sub>	V <sub>GS</sub> = -10 V	$I_D = -1 \ 8 \ A,$ $V_{DS} = -48 \ V,$	-	-	9.9	
Gate-Drain Charge	$Q_{gd}$		see fig. 6 and 13 b	-	-	16	
Turn-On Delay Time	t <sub>d(on)</sub>		l .	-	18	-	
Rise Time	t <sub>r</sub>	$V_{DD}$ = -30 V, $I_{D}$ = -18 A, $R_{g}$ = 12 $\Omega$ , $R_{D}$ = 1.5 $\Omega$ , see fig. 10 <sup>b</sup>		_	120	-	- ns
Turn-Off Delay Time	t <sub>d(off)</sub>			-	20		
Fall Time	t <sub>f</sub>			-	58	-	
Internal Drain Inductance	L <sub>D</sub>		Between lead, 6 mm (0.25") from package and center of die contact		4.5	-	ьЦ
Internal Source Inductance	L <sub>S</sub>				7.5	-	nH
Gate Input Resistance	$R_g$	f = 1 MHz, open drain		0.7	-	3.9	Ω
Drain-Source Body Diode Characteristic	cs						
Continuous Source-Drain Diode Current	I <sub>S</sub>	MOSFET symbol showing the integral reverse p -n junction diode		-	-	-18	A
Pulsed Diode Forward Current <sup>a</sup>	I <sub>SM</sub>			-	-	-72	
Body Diode Voltage	V <sub>SD</sub>	$T_J = 25 ^{\circ}\text{C}, I_S$	$=$ -18 A, $V_{GS} = 0 V^b$	-	-	-6.3	V
Body Diode Reverse Recovery Time	t <sub>rr</sub>	T 25 °C 1 -	18 A dl/dt = 100 A/va b	-	100	200	ns
Body Diode Reverse Recovery Charge	Q <sub>rr</sub>	- T <sub>J</sub> = 25 °C, I <sub>F</sub> = -18 A, dI/dt = 100 A/µs b		-	0.28	0.52	μC
Forward Turn-On Time	t <sub>on</sub>	Intrinsic turn-	rn-on is dominated by $L_S$ and $L_E$			L <sub>D</sub> )	

### Notes

- a. Repetitive rating; pulse width limited by maximum junction temperature (see fig. 11).
- b. Pulse width  $\leq$  300  $\mu$ s; duty cycle  $\leq$  2 %.



## TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

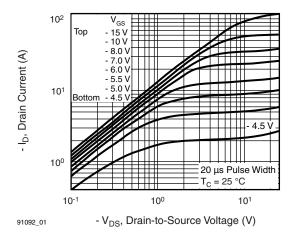


Fig. 1 - Typical Output Characteristics, T<sub>C</sub> = 25 °C

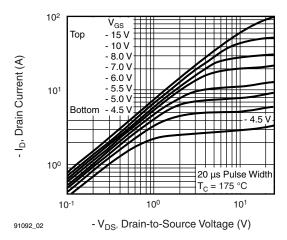


Fig. 2 - Typical Output Characteristics,  $T_C = 175$  °C

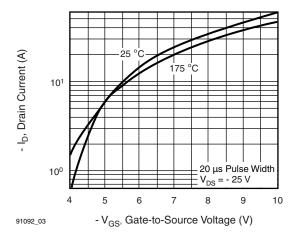


Fig. 3 - Typical Transfer Characteristics

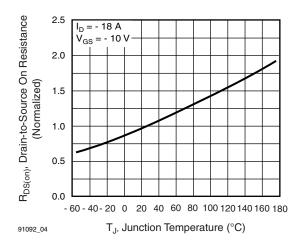


Fig. 4 - Normalized On-Resistance vs. Temperature

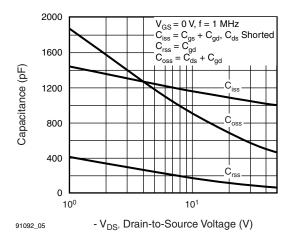


Fig. 5 - Typical Capacitance vs. Drain-to-Source Voltage

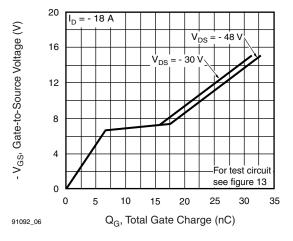


Fig. 6 - Typical Gate Charge vs. Gate-to-Source Voltage



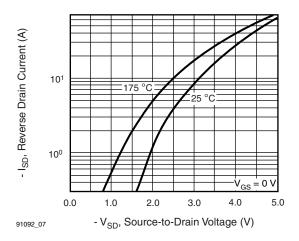


Fig. 7 - Typical Source-Drain Diode Forward Voltage

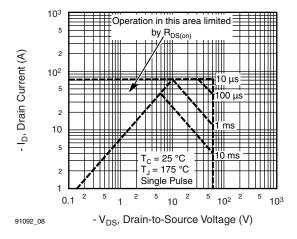


Fig. 8 - Maximum Safe Operating Area

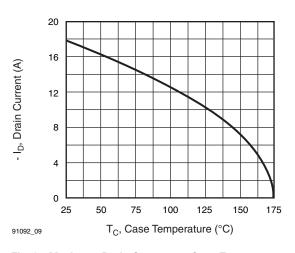


Fig. 9 - Maximum Drain Current vs. Case Temperature

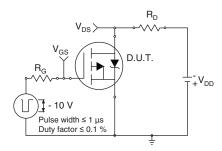


Fig. 10a - Switching Time Test Circuit

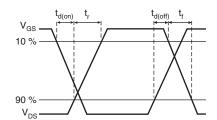


Fig. 10b - Switching Time Waveforms

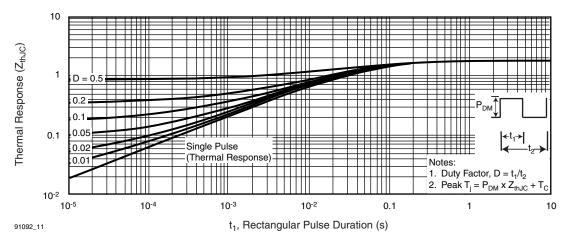


Fig. 11 - Maximum Effective Transient Thermal Impedance, Junction-to-Case



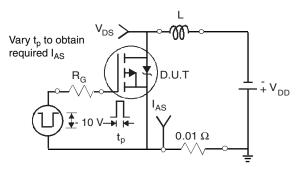


Fig. 12a - Unclamped Inductive Test Circuit

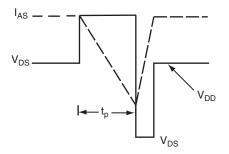


Fig. 12b - Unclamped Inductive Waveforms

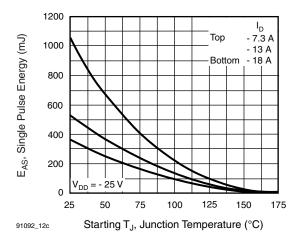


Fig. 12c - Maximum Avalanche Energy vs. Drain Current

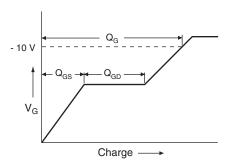


Fig. 13a - Basic Gate Charge Waveform

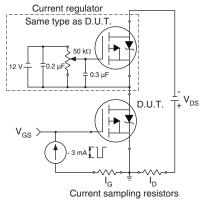
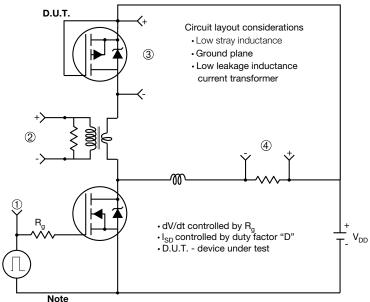


Fig. 13b - Gate Charge Test Circuit



## Peak Diode Recovery dV/dt Test Circuit



• Compliment N-Channel of D.U.T. for driver

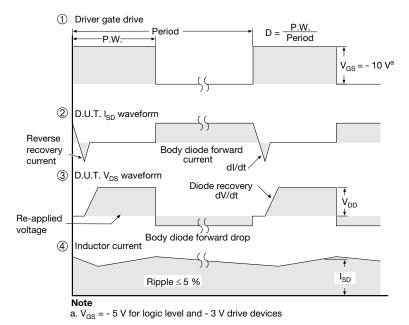


Fig. 14 - For P-Channel

Vishay Siliconix maintains worldwide manufacturing capability. Products may be manufactured at one of several qualified locations. Reliability data for Silicon Technology and Package Reliability represent a composite of all qualified locations. For related documents such as package/tape drawings, part marking, and reliability data, see <a href="http://www.vishay.com/ppg?91092">http://www.vishay.com/ppg?91092</a>.





# TO-220-1



DIM	MILLIN	IETERS	INCHES		
DIM.	MIN.	MAX.	MIN.	MAX.	
Α	4.24	4.65	0.167	0.183	
b	0.69	1.02	0.027	0.040	
b(1)	1.14	1.78	0.045	0.070	
С	0.36	0.61	0.014	0.024	
D	14.33	15.85	0.564	0.624	
E	9.96	10.52	0.392	0.414	
е	2.41	2.67	0.095	0.105	
e(1)	4.88	5.28	0.192	0.208	
F	1.14	1.40	0.045	0.055	
H(1)	6.10	6.71	0.240	0.264	
J(1)	2.41	2.92	0.095	0.115	
L	13.36	14.40	0.526	0.567	
L(1)	3.33	4.04	0.131	0.159	
ØР	3.53	3.94	0.139	0.155	
Q	2.54	3.00	0.100	0.118	
ECN: X15-0364-Rev. C, 14-Dec-15 DWG: 6031					

## Note

 $\bullet$   $M^{\star}=0.052$  inches to 0.064 inches (dimension including protrusion), heatsink hole for HVM



Revison: 14-Dec-15 1 Document Number: 66542



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